503138338 01/15/2015

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
BING WANG	01/17/2013
KUOYUAN (PETER) HSU	01/17/2013

RECEIVING PARTY DATA

Name:	TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY, LTD.	
Street Address:	NO. 8, LI-HSIN RD. VI, HSINCHU SCIENCE PARK	
City:	HSINCHU	
State/Country:	TAIWAN	
Postal Code:	300	

PROPERTY NUMBERS Total: 1

Property Type	Number	
Application Number:	14597897	

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ATTORNEY DOCKET NUMBER:	T5057-763UA
NAME OF SUBMITTER:	RANDY A. NORANBROCK
SIGNATURE:	/Randy A. Noranbrock/
DATE SIGNED:	01/15/2015

Total Attachments: 1

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PATENT 503138338 REEL: 034729 FRAME: 0381

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Docket No. T5057-763U TSMC2012-0271

ASSIGNMENT

In consideration of the premises and other good and valuable consideration in hand paid, the receipt and sufficiency of which is hereby acknowledged, the undersigned,

- 1) Bing WANG
- 2) Kuoyuan (Peter) HSU

MANU 300, Ta its succ	as made a certain new and useful invention, hereby sells, assigns and transfers unto TJFACTURING COMPANY, LTD., having a place of business at No. 8, Li-Hsin Rd. VI., laiwan R.O.C. bessors and assigns (hereinafter designated "ASSIGNEE") the entire right, title and interest fined in 35 U.S.C. 100 in the invention entitled	Hsinchu Science Park, Hsinchu
<u>swi</u>	TCHING CIRCUIT	
(a)	for which an application for United States Letters Patent was filed on 2013-02-12 United States Patent Application No. 13/765, 475; or	, and identified by
(b)	for which an application for United States Letters Patent was executed on,	
all Unit	e unders gned hereby authorizes and requests the United States Commissioner of Patents are ted States Letters Patent which may be granted therefore and any and all extensions, divisuations-in-part thereof, and the right to all benefits under the International Convention by to the said ASSIGNEE, for its interest as ASSIGNEE, its successors, assigns and legal response.	ions, reissues, continuations, or for the Protection of Industrial

AND the undersigned hereby agrees to transfer a like interest, and to render all necessary assistance in making application for and obtaining original, divisional, reissued or extended Letters Patent of the United States, upon request of the said ASSIGNEE, it successors, assigns and legal representatives, and without further remuneration, in and to any improvements, and applications for patent based thereon, growing out of or related to the said invention; and to execute any papers by the said ASSIGNEE, it successors, assigns and legal representatives, deemed essential to ASSIGNEE's full protection and title in and to the invention hereby transferred.

agrees that the attorneys of record in said application shall hereafter act on behalf of said ASSIGNEE;

PATENT REEL: 034729 FRAME: 0382